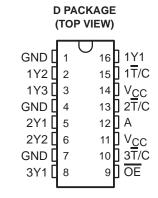
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- Low Output Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and Outputs
- Distributes One Clock Input to Six Clock Outputs
- Polarity Control Selects True or Complementary Outputs
- Distributed V_{CC} and GND Pins Reduce Switching Noise
- High-Drive Outputs (-48-mA I_{OH}, 48-mA I_{OL})
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Packaged in Plastic Small-Outline Package



description

The CDC391 contains a clock-driver circuit that distributes one input signal to six outputs with minimum skew for clock distribution. Through the use of the polarity-control (\overline{T}/C) inputs, various combinations of true and complementary outputs can be obtained. The output-enable (\overline{OE}) input is provided to disable the outputs to a high-impedance state.

The CDC391 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE

	INPUTS	OUTPUT	
OE	T/C	Α	Y
Н	Х	Χ	Z
L	L	L	L
L	L	Н	Н
L	Н	L	Н
L	Н	Н	L

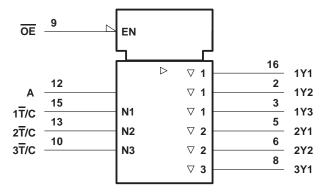


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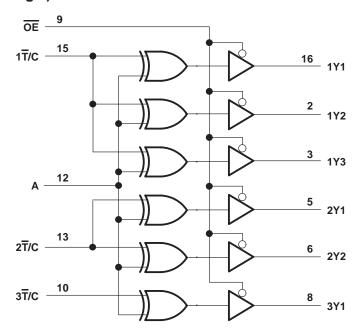


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	\dots -0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, $V_0 \dots -0$.	5 V to V _{CC} + 0.5 V
Current into any output in the low state, IO	96 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 2)	0.77 W
Storage temperature range, T _{stq}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
VI	Input voltage	0		VCC	V
I _{OH}	High-level output current			-48	mA
I _{OL}	Low-level output current			48	mA
Δt/Δν	Input transition rise or fall rate			5	ns/V
fclock	Input clock frequency			100	MHz
TA	Operating free-air temperature	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	TYP [‡]	MAX	UNIT		
VIK	$V_{CC} = 4.75 \text{ V},$	I _I = -18 mA				-1.2	V
Voн	$V_{CC} = 4.75 \text{ V},$	I _{OH} = – 48 mA		2			V
V _{OL}	$V_{CC} = 4.75 \text{ V},$	I _{OL} = 48 mA				0.5	V
I _I	$V_{CC} = 5.25 \text{ V},$	$V_1 = V_{CC}$ or GND				±1	μΑ
loz	$V_{CC} = 5.25 \text{ V},$	$V_O = V_{CC}$ or GND				±50	μΑ
ΙΟ [§]	$V_{CC} = 5.25 \text{ V},$	V _O = 2.5 V		-15		-100	mA
			Outputs high			10	
Icc	$V_{CC} = 5.25 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$	$I_{O}=0,$	Outputs low			40	mA
	V1 = VCC 01 014D		Outputs disabled			10	
C _i	V _I = 2.5 V or 0.5 V	·	·		3		pF
Co	V _O = 2.5 V or 0.5 V		<u> </u>		5		pF

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 300 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

CDC391 1-LINE TO 6-LINE CLOCK DRIVER WITH SELECTABLE POLARITY AND 3-STATE OUTPUTS

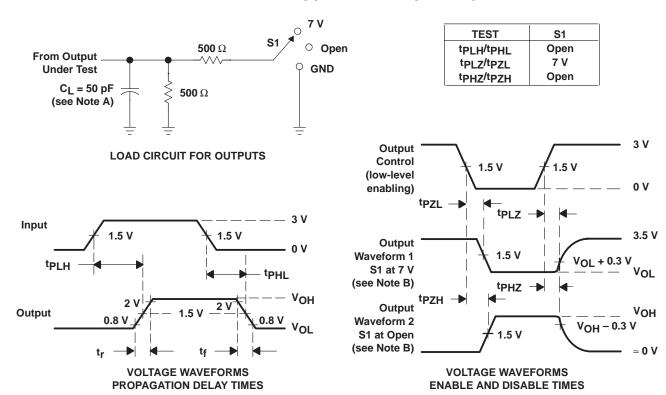
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)			UNIT
t _{PLH}	A	Any Y	1.5	5	no
t _{PHL}	A	Ally f	1.5	5	ns
t _{PLH}	T/C	Any Y	1.5	5	
^t PHL	1/C	Any f	1.5	5	ns
^t PZH	ŌĒ	Any Y	1.5	5	no
tPZL	OE	Ally f	3	7	ns
t _{PHZ}	ŌĒ	Any Y		5	no
t _{PLZ}	OE	Ally f		5	ns
* * * *	А	Any Y (same phase)		0.5	no
^t sk(o)	A	Any Y (any phase)		1	ns
^t sk(p)	Α	Any Y		1	ns
t _r				1.5	ns
t _f				1.5	ns



PARAMETER MEASUREMENT INFORMATION

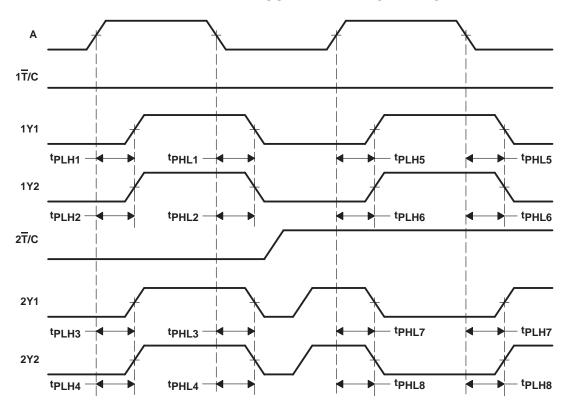


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Output skew, $t_{Sk(0)}$, from A to any Y (same phase), can be measured only between outputs for which the respective polarity-control inputs (\overline{T}/C) are at the same logic level. It is calculated as the greater of:
 - The difference between the fastest and slowest of tpLH from A↑ to any Y (e.g., tpLHn, n = 1 to 4; or tpLHn, n = 5 to 6)
 - The difference between the fastest and slowest of tPHL from A↓ to any Y (e.g., tPHLn, n = 1 to 4; or tPHLn, n = 5 to 6)
 - The difference between the fastest and slowest of tp_{LH} from A↓ to any Y (e.g., tp_{LHn}, n = 7 to 8)
 - The difference between the fastest and slowest of tp_{HL} from A↑ to any Y (e.g., tp_{HLn}, n = 7 to 8)
 - B. Output skew, t_{Sk(o)}, from A to any Y (any phase), can be measured between outputs for which the respective polarity-control inputs (T/C) are at the same or different logic levels. It is calculated as the greater of:
 - The difference between the fastest and slowest of tp_{LH} from A[↑] to any Y or tp_{HL} from A[↑] to any Y (e.g., tp_{LHn}, n = 1 to 4; or tp_{LHn}, n = 5 to 6, and tp_{HLn}, n = 7 to 8)
 - The difference between the fastest and slowest of tp_{HL} from A↓ to any Y or tp_{LH} from A↓ to any Y (e.g., tp_{HLn}, n = 1 to 4; or tp_{HLn}, n = 5 to 6, and tp_{LHn}, n = 7 to 8)

Figure 2. Waveforms for Calculation of t_{sk(o)}







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CDC391D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC391DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC391DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC391DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

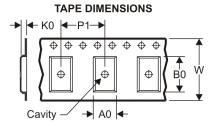
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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC391DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC391DR	SOIC	D	16	2500	346.0	346.0	33.0

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